

Dynasolve™ 2000



Cured Polymer Cleaning Solvent



Dynasolve 2000 is a reactive formulated solvent that is used to remove anhydride-cured epoxy, urethane, and silicone. It is used in both industrial and electronic applications. It is aluminum-safe for a 24-hour period.

CLEANING APPLICATIONS:

Depotting and decapsulating of electronic components
Industrial polymer removal and cleaning

ADVANTAGES:

All-in-one product works on several types of polymers
More efficient than acetone, MEK & other solvents
Formulated to be highly selective
Aluminum safe for 24hr period
High flash point

SPECIFICATIONS:

Specific gravity:	1.07
Boiling point:	482°F (250°C)
Flash point:	217°F (103°C)

MATERIALS REMOVED:

Anhydride-cured epoxy
Urethane
Silicone

PRODUCT USAGE GUIDELINES

(SEE SDS FOR EH&S INFORMATION)

1. Heat Dynasolve 2000 and immerse part.
 - Heat to 245°F (118°C) for anhydride cured epoxy
 - Heat to 200°F (93°C) for urethane or silicone
3. Observe carefully. If polymer appears unaffected after 1 hour, increase temperature to 250° – 300°F (121° – 148°C).
4. After successful removal of material, rinse with alcohol or water.
5. If polymer appears unaffected after 2 hours, call for technical support.

MATERIAL COMPATIBILITY:

Recommended materials including:

Most metals
Teflon®
Polyethylene & polypropylene

Avoid materials including:

Galvanized steel
PVC
Liquid isocyanate



For more information, please contact us at:

VERSUM MATERIALS, LLC
VERSUMMATERIALS.COM

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